

BAR 28

SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

Metal to silicon junction diode featuring high breakdown, low turn-on voltage and ultrafast switching. Primarly intended for high level UHF/VHF detection and pulse application with broad dynamic range. Matched batches are available on request.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
V_{RRM}	Repetitive Peak Reverse Voltage	70	٧	
l _F	Forward Continuous Current*	15	mA	
I _{FSM}	Surge non Repetitive Forward Current*	$t_p \le 1s$	50	mA
T _{stg}	Storage and Junction Temperature Range	- 65 to 200 - 65 to 200	°C	
\\\T _L	Maximum Lead Temperature for Soldering of from Case	230	°C	

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R _{th(j-a)}	Junction-ambient*	400	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	To	Min.	Тур.	Max.	Unit	
V _{BR}	$T_{amb} = 25^{\circ}C$ $I_{R} =$	= 10μA	70		-55	V
V _F * *	$T_{amb} = 25^{\circ}C$ $I_{F} =$: 1mA		da-	0.41	V
	$T_{amb} = 25^{\circ}C$ $I_{F} =$: 15mA		WW	W-D-	
I _R * *	$T_{amb} = 25^{\circ}C$ V_{R}	= 50V			0.2	μΑ

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions				Тур.	Max.	Unit
С	T _{amb} = 25°C	$V_R = 0V$	f = 1MHz			2	pF
τ	T _{amb} = 25°C	$I_F = 5mA$	Krakauer Method			100	ps

^{*} On infinite heatsink with 4mm lead length

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^{**} Pulse test: $t_p \le 300 \mu s$ $\delta < 2\%$.

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

Figure 1. Forward current versus forward voltage at low level (typical values).

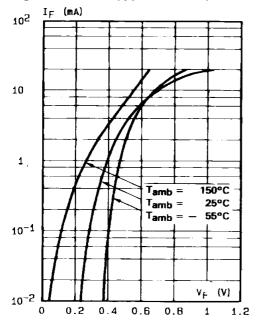


Figure 2. Capacitance C versus reverse applied voltage V_R (typical values).

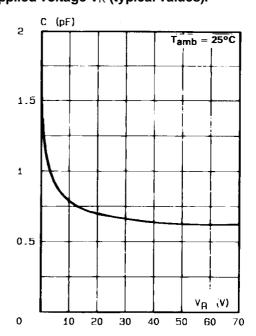


Figure 3. Reverse current versus ambient temperature.

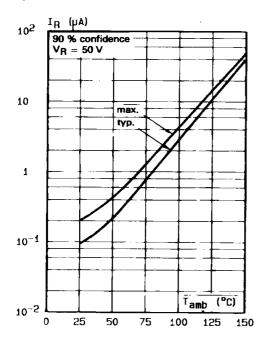
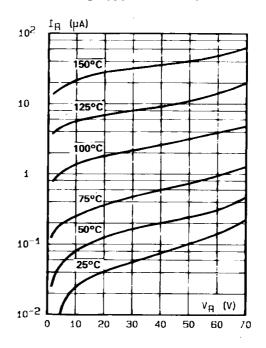
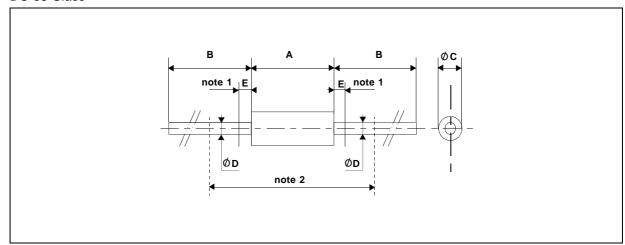


Figure 4. Reverse current versus continuous reverse voltage (typical values).



PACKAGE MECHANICAL DATA

DO 35 Glass



	DIMENSIONS						
REF.	- Millimeters		s Inches		NOTES		
	Min.	Max.	Min.	Max.			
Α	3.050	4.500	0.120	0.117	1 - The lead diameter Ø D is not controlled over zone E		
В	12.7		0.500		2 - The minimum axial lengh within which the device may be		
ØC	1.530	2.000	0.060	0.079	placed with its leads bent at right angles is 0.59"(15 mm)		
ØD	0.458	0.558	0.018	0.022			
Е		1.27		0.050			

Cooling method: by convection and conduction Marking: clear, ring at cathode end.

Weight: 0.15g

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